

RKD700KJ

Silicon Schottky Barrier Diode for Backflow prevention

REJ03G1301-0100 Rev.1.00 Oct 24, 2005

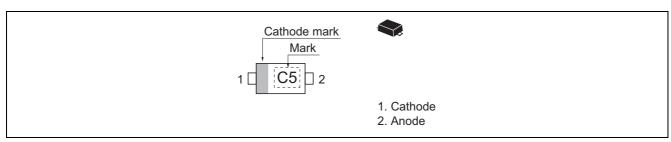
Features

- Low reverse current, Low capacitance.
- Ultra small Flat Lead Package (UFP) is suitable for surface mount design.

Ordering Information

Type No.	Cathode Mark	Package Name	Package Code (Previous Code)
RKD700KJ	C5	UFP	PWSF0002ZA-A
			(UFP)

Pin Arrangement



Absolute Maximum Ratings

 $(Ta = 25^{\circ}C)$

Item	Symbol	Value	Unit
Repetitive peak reverse voltage	V_{RRM}	30	V
Reverse voltage	V _R	30	V
Non-Repetitive peak forward surge current	I _{FSM} *	200	mA
Average rectified current	I ₀	50	mA
Junction temperature	Tj	125	°C
Storage temperature	Tstg	-55 to +125	°C

Note: 10 ms Sinewave 1 pulse

Electrical Characteristics

 $(Ta = 25^{\circ}C)$

Item	Symbol	Min	Тур	Max	Unit	Test Condition
Forward voltage	V_{F1}	_	0.11	0.14	V	$I_F = 1 \mu A$
	V_{F2}	_	_	0.33		I _F = 1 mA
	V_{F3}	_	_	0.43		I _F = 10 mA
Reverse current	I _{R1}	_		45	nA	V _R = 3 V
	I _{R2}	_		1	μΑ	V _R = 30 V
Capacitance	С	_		2.8	pF	V _R = 1 V, f = 1 MHz

Note: 1. For UFP package, the material of lead is exposed for cutting plane. There for, soldering nature of lead tip part is considered as unquestioned. Please kindly consider soldering nature.

Main Characteristic

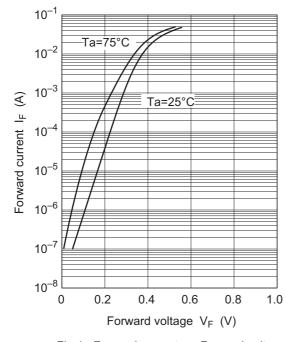
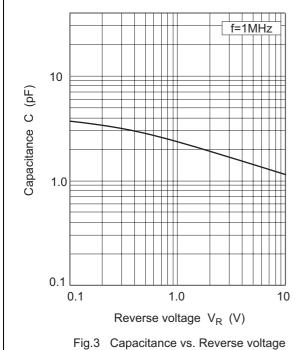


Fig.1 Forward current vs. Forward voltage



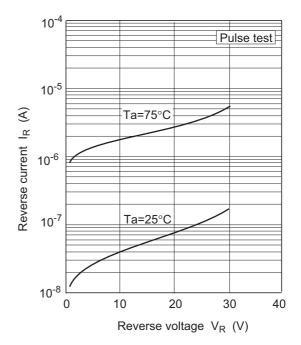
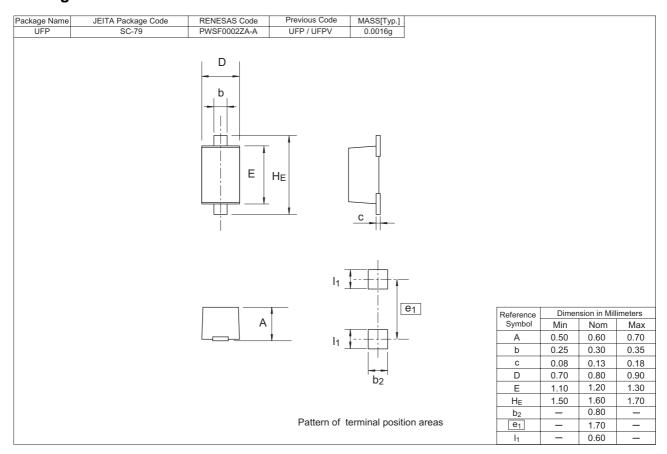


Fig.2 Reverse current vs. Reverse voltage

Package Dimensions



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